- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

	TYPICAL AVERAGE	TYPICAL
TYPE	PROPAGATION	TOTAL POWER
	DELAY TIME	DISSIPATION
'86	14 ns	150 mW
'LS86A	10 ns	30.5 mW
'S86	7 ns	250 mW

#### description

These devices contain four independent 2-input Exclusive-OR gates. They perform the Boolean functions  $Y = A \oplus B = \overline{AB} + A\overline{B}$  in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input will be reproduced in true form at the output. If one of the inputs is high, the signal on the other input will be reproduced inverted at the output.

The SN5486, 54LS86A, and the SN54S86 are characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN7486, SN74LS86A, and the SN74S86 are characterized for operation from 0 °C to 70 °C.

#### exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



**EXCLUSIVE-OR** 

These are five equivalent Exclusive-OR symbols valid for an '86 or 'LS86A gate in positive logic; negation may be shown at any two ports.

LOGIC IDENTITY ELEMENT



The output is active (low) if all inputs stand at the same logic level (i.e., A = B).

**EVEN-PARITY** 



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

**ODD-PARITY ELEMENT** 

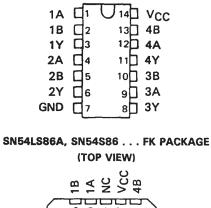


The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

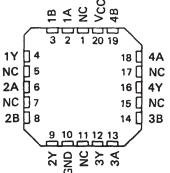




SN5486, SN54LS86A, SN54S86 . . . J OR W PACKAGE

SN7486 . . . N PACKAGE SN74LS86A, SN74S86 . . . D OR N PACKAGE

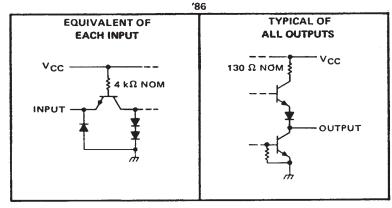
(TOP VIEW)



NC - No internal connection

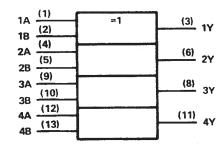
## OBSOLETE - No Longer Available SN5486, SN54LS86A, SN54S86 SN7486, SN74LS86A, SN74S86 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES SDLS124 – DECEMBER 1972 – REVISED MARCH 1988

## schematics of inputs and outputs



'LS86A

## logic symbol<sup>†</sup>



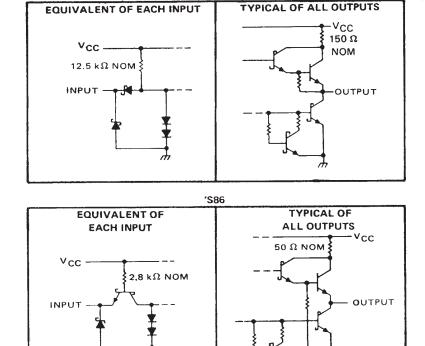
<sup>†</sup>This symbol is in accordance with

ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

#### FUNCTION TABLE

INP	UTS	OUTPUT
Α	В	Y
L	L	L
L	н	н
н	L	н
н	н	L

H = high level, L = low level



# OBSOLETE - No Longer Available SN5486, SN54LS86A, SN54S86 SN7486, SN74LS86A, SN74S86 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)																				7	V
Input voltage																					
Operating free-air temperature range: SN5486																					
SN7486																					
Storage temperature range	•	•	•	•	•	•		•	•	•	•	•	•	•	•	•	_	65°(	C to	150	°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN5486	5		SN748	5	UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-800			-800	μA
Low-level output current, IOL			16			16	mA
Operating free-air temperature, TA	55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS <sup>†</sup>		SN5486	5		UNIT		
	PARAMETER	TEST CONDITIONS'	MIN	TYP‡	MAX	MIN	TYP‡	MAX	
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			0.8	V
VIK	Input clamp voltage	$V_{CC} = MIN$ , $I_1 = -8 mA$			-1.5			-1.5	V
		$V_{CC} = MIN, V_{IH} = 2V,$	24	3.4		2.4	3.4		V
∨он	High-level output voltage	$V_{1L} = 0.8 V$ , $I_{OH} = -800 \mu A$	2.4	3.4		2.4	3.4		ľ
		V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V		0.2	0.4		0.2	0.4	V
VOL	Low-level output voltage	V1L = 0.8 V, 10L = 16 mA		0.2	0.4		0.2	0.4	
4	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V			1			1	mA
1 <sub>IH</sub>	High-level input current	V <sub>CC</sub> = MAX, V <sub>1</sub> = 2.4 V			40			40	μA
11L	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V			-1.6			-1.6	mA
los	Short-circuit output current §	V <sub>CC</sub> = MAX	20		-55	-18		-55	mA
1CC	Supply current	V <sub>CC</sub> = MAX, See Note 2		30	43		30	50	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. <sup>‡</sup>All typical values are at  $V_{CC} = 5 V$ ,  $T_A = 25^{\circ}C$ .

SNot more than one output should be shorted at a time.

NOTE 2: ICC is measured with the inputs grounded and the outputs open.

## switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = $25^{\circ}$ C

PARAMETER	FROM (INPUT)	TEST COM	DITIONS	MIN	түр	мах	UNIT	
<sup>t</sup> PLH	A or B	Other in put low	CL = 15 pF,		15	23	ns	
<sup>t</sup> PHL	AUB	Other input low	$R_{L} = 400 \Omega,$		11	17		
tPLH	A or B	Other insut high	See Note 3			18	30	ns
tPHL .	AUB	Other input high	See Note S		13	22		

 $\P_{tpLH}$  = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



# OBSOLETE - No Longer Available SN5486, SN54LS86A, SN54S86 SN7486, SN74LS86A, SN74S86 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)	
Input voltage	V
Operating free-air temperature range: SN54LS86A	°C
SN74LS86A	
Storage temperature range	°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

	S	N54LS	36A	S	SN74LS86A				
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT		
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	V		
High-level output current, IOH			-400			-400	μA		
Low-level output current, IOL			4			8	mA		
Operating free-air temperature, TA	-55		125	0		70	°C		

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			upizionist	SM	154LS8	6A	SM	UNIT		
	PARAMETER	TEST CO	NDITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	
ViH	High-level input voltage			2			2			V
VIL	Low-level input voltage			1		0.7			0.8	V
Vik	Input clamp voltage	V <sub>CC</sub> = MIN,	li = -18 mA	1		-1.5			-1.5	V
VOH	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max	V <sub>IH</sub> = 2 V, , I <sub>OH</sub> = -400 µA	2.5	3.4		2.7	3.4		v
Mai	Low-level output voltage	$V_{CC} = MIN,$ $V_{IH} = 2 V,$	1 <sub>0L</sub> = 4 mA		0.25	0.4		0.25	0.4	
VOL		$V_{IL} = V_{IL}max$	1 <sub>OL</sub> = 8 mA					0.35	0.5	
4	Input current at maximum input voltage	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V	1		0.2	T		0.2	mA
Чн	High-level input current	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V			40			40	μA
4	Low-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V	1		0.8			-0.8	mA
los	Short-circuit output current <sup>§</sup>	V <sub>CC</sub> = MAX		- 20		- 100	- 20		- 100	mA
Icc	Supply current	V <sub>CC</sub> = MAX,	See Note 2	1	6.1	10		6.1	10	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. <sup>‡</sup>All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}$ C.

SNot more than one output should be shorted at a time.

NOTE 2:  $I_{CC}$  is measured with the inputs grounded and the outputs open.

### switching characteristics, $V_{CC} = 5 V$ , $T_A = 25^{\circ}C$

PARAMETER¶	FROM (INPUT)	TEST CON	MIN	түр	MAX	UNIT		
tPLH	A or B	Orber input low	$C_{\rm r} = 15  \rm nE$		12	23	ns	
<sup>t</sup> PHL	AUB	Other input low	$C_{L} = 15  pF,$	[	10	17		
<sup>t</sup> PLH	A or B	Other input high	$R_L = 2 k Q$ ,	Other input high See Note 3		20	30	ns
<sup>t</sup> PHL	AOID	Other input high	See Note 5	[·	13	22		

 $\P_{tp_{LH}}$  = propagation delay time, low-to-high-level output

tpHL == propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



## OBSOLETE - No Longer Available SN5486, SN54LS86A, SN54S86 SN7486, SN74LS86A, SN74S86 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES SDLS124 - DECEMBER 1972 - REVISED MARCH 1988

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)	 												7 V
Input voltage	 												5.5 V
Operating free-air temperature range: SN54S86	 	•			•			 •				–55°C to	125°C
SN74S86	 	•						 •	-	•	•	. 0°C t	o 70°C
Storage temperature range	 	•	•••		•		•	 •	•	•		–65°C to	150°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN54S8	6		UNIT		
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-1			-1	mA
Low-level output current, IOL			20			20	mA
Operating free-air temperature, TA	-55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS!		SN54S8	6		SN74S8	6	
	PARAMETER	TEST CONDITIONS <sup>†</sup>	MIN	TYP‡	MAX	MIN	TYP‡	MAX	
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			0.8	V
VIK	Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>1</sub> =18 mA			-1.2			-1.2	V
VOH	High-level output voltage	$V_{CC} = MIN, V_{1H} = 2V,$ $V_{11} = 0.8V, I_{OH} = -1 mA$	2.5	3.4		2.7	3.4		v
VOL	Low-level output voltage	$V_{CC} = MIN, V_{1H} = 2 V$ $V_{1L} = 0.8 V, I_{0L} = 20 mA$	1		0.5			0.5	v
4	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>1</sub> = 5.5 V	<u> </u>		1			1	mA
<u>ч</u> н	High-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V			50			50	μA
11	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V	1		-2	1		-2	mA
los	Short-circuit output current §	V <sub>CC</sub> = MAX	-40		-100	-40		-100	mA
	Supply current	V <sub>CC</sub> = MAX, See Note 2		50	75		50	75	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. <sup>‡</sup>All typical values are at  $V_{CC} = 5 V$ ,  $T_A = 25^{\circ}C$ .

Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: ICC is measured with the inputs grounded and the outputs open.

#### switching characteristics, $V_{CC} = 5 V$ , $T_A = 25^{\circ}C$

PARAMETER	FROM (INPUT)	TEST CONDITIONS				MAX	UNIT
tрсн	A or B	Other input low	C1 = 15 pF,		7	10.5	ns
tPHL		Other input low	R <sub>L</sub> = 280 Ω,		6.5	10	ļ
tplH	A or B	Other input high	See Note 3		7	10.5	ns
трнг		Other input night			6.5	10	

ItpLH = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





23-Sep-2013

# **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/07501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07501BCA	Samples
JM38510/07501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07501BDA	Samples
JM38510/07501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07501BDA	Samples
JM38510/30502B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30502B2A	Samples
JM38510/30502B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30502B2A	Samples
JM38510/30502BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30502BCA	Samples
JM38510/30502BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30502BCA	Samples
JM38510/30502BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30502BDA	Samples
JM38510/30502BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30502BDA	Samples
M38510/07501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07501BCA	Samples
M38510/07501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07501BCA	Samples
M38510/07501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07501BDA	Samples
M38510/07501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07501BDA	Samples
M38510/30502B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30502B2A	Samples
M38510/30502B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30502B2A	Samples
M38510/30502BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30502BCA	Samples
M38510/30502BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30502BCA	Samples



# PACKAGE OPTION ADDENDUM

23-Sep-2013

Orderable Device		Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish		Op Temp (°C)	Device Marking	Sample
	(1)					(2)		(3)		(4/5)	
M38510/30502BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30502BDA	Sample
M38510/30502BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30502BDA	Sample
SN5486J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125	SN5486J	
SN5486J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125	SN5486J	
SN54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS86AJ	Sample
SN54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS86AJ	Sampl
SN54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S86J	Sampl
SN54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S86J	Sampl
SN7486N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7486N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7486N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7486N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS86AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS86A	Sampl
SN74LS86AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS86A	Sampl
SN74LS86ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS86A	Sampl
SN74LS86ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS86A	Sampl
SN74LS86ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS86A	Sampl
SN74LS86ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS86A	Sampl
SN74LS86ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS86A	Sampl
SN74LS86ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS86A	Sampl
SN74LS86ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS86A	Samp



# PACKAGE OPTION ADDENDUM

23-Sep-2013

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS86ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS86A	Samples
SN74LS86ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS86A	Samples
SN74LS86ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS86A	Samples
SN74LS86AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS86AN	Samples
SN74LS86AN	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS86AN	Samples
SN74LS86AN3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	0 to 70		
SN74LS86AN3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	0 to 70		
SN74LS86ANE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS86AN	Samples
SN74LS86ANE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS86AN	Samples
SN74LS86ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS86A	Samples
SN74LS86ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS86A	Samples
SN74LS86ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS86A	Samples
SN74LS86ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS86A	Samples
SN74LS86ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS86A	Samples
SN74LS86ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS86A	Samples
SN74S86D	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S86	
SN74S86D	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S86	
SN74S86DE4	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S86	
SN74S86DE4	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S86	



# PACKAGE OPTION ADDENDUM

23-Sep-2013

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74S86DG4	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S86	
SN74S86DG4	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S86	
SN74S86N	NRND	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S86N	
SN74S86N	NRND	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S86N	
SN74S86N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	0 to 70		
SN74S86N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	0 to 70		
SN74S86NE4	NRND	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S86N	
SN74S86NE4	NRND	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S86N	
SNJ5486J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125	SNJ5486J	
SNJ5486J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125	SNJ5486J	
SNJ5486W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125	SNJ5486W	
SNJ5486W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125	SNJ5486W	
SNJ54LS86AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 86AFK	Samples
SNJ54LS86AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 86AFK	Samples
SNJ54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS86AJ	Samples
SNJ54LS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS86AJ	Samples
SNJ54LS86AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS86AW	Samples
SNJ54LS86AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS86AW	Samples
SNJ54S86FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 86FK	Samples
SNJ54S86FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 86FK	Samples
SNJ54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S86J	Samples



23-Sep-2013

Orderable Device	Status (1)	Package Type	Package Drawing		Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54S86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S86J	Samples
SNJ54S86W	NRND	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S86W	
SNJ54S86W	NRND	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S86W	

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN5486, SN54LS86A, SN54S86, SN7486, SN74LS86A, SN74S86 :



www.ti.com

# PACKAGE OPTION ADDENDUM

23-Sep-2013

#### • Catalog: SN7486, SN74LS86A, SN74S86

• Military: SN5486, SN54LS86A, SN54S86

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# PACKAGE MATERIALS INFORMATION

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# TAPE AND REEL INFORMATION





# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal
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Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS86ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TEXAS INSTRUMENTS

www.ti.com

# PACKAGE MATERIALS INFORMATION

8-Apr-2013



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS86ADR	SOIC	D	14	2500	367.0	367.0	38.0

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N\*\*) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# MECHANICAL DATA

## PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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